

Vishay General Semiconductor

HALOGEN

FREE

Surface-Mount Glass Passivated Rectifier



SMB (DO-214AA)



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS					
I _{F(AV)}	3.0 A				
V_{RRM}	400 V, 600 V, 800 V, 1000 V				
I _{FSM}	90 A				
I _R	5.0 μA				
V_F at $I_F = 3.0 \text{ A}$	0.88 V				
T _J max.	150 °C				
Package	SMB (DO-214AA)				
Circuit configuration	Single				

FEATURES

- Low profile package
- · Ideal for automated placement
- · Glass passivated chip junction
- Low forward voltage drop
- Low leakage current
- · High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

TYPICAL APPLICATIONS

For use in general purpose rectification of power supplies, inverters, converters and freewheeling diodes for consumer, medical and telecommunication.

MECHANICAL DATA

Case: SMB (DO-214AA)

Molding compound meets UL 94 V-0 flammability rating Base P/N-E3 - RoHS compliant, commercial grade

Base P/N-M3 - halogen-free, RoHS compliant, and commercial grade

Terminals: matte tin plated leads, solderable

J-STD-002 and JESD 22-B102

E3 and M3 suffix meets JESD 201 class 1A whisker test

Polarity: color band denotes the cathode end

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	S3BG	S3BJ	S3BK	S3BM	UNIT
Device marking code		3G	3J	3K	3M	
Maximum repetitive peak reverse voltage	V_{RRM}	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	280	420	560	700	V
Marina PO (see and a seed (fee 4)		3.0				Α
Maximum DC forward current (fig. 1)	I _F ⁽²⁾	1.4				Α
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM} 90			Α		
perating and storage temperature range T _J (3), T _{STG} -55 to +150				°C		

Notes

- (1) Mounted on 20 mm x 20 mm pad areas, 2 oz. FR4 PCB
- (2) Free air mounted on recommended copper pad area
- (3) The heat generated must be less than the thermal conductivity from junction-to-ambient: dPD/dTJ < 1/ReJA



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ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)							
PARAMETER	TEST CO	TEST CONDITIONS		TYP.	MAX.	UNIT	
Instantaneous forward voltage	I _F = 1.5 A	T _J = 25 °C	V _F ⁽¹⁾	0.90	-	V	
	I _F = 3.0 A			0.97	1.1		
	I _F = 1.5 A	T _J = 125 °C		0.79	-		
	I _F = 3.0 A			0.88	1.0		
Reverse current	Rated V _R	T _J = 25 °C	I _R ⁽²⁾	0.17	5.0	- μΑ	
	naleu v _R	T _J = 125 °C		40	200		
Typical reverse recovery time	$I_F = 0.5 A, I_R = 1$ $I_{rr} = 0.25 A$	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A},$ $I_{rr} = 0.25 \text{ A}$		2.5		μs	
Typical junction capacitance	Rated V _R = 4.0	Rated V _R = 4.0 V, 1 MHz		22		pF	

Notes

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width, ≤ 40 ms

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	S3BG	S3BJ	S3BK	S3BM	UNIT	
Typical thermal resistance	R ₀ JA (1)(2)	107				°C/W	
Typical trieffilal resistance	R _{0JM} (3)	7.2				C/VV	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta,JA}$
- (2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz. standard footprint
- (3) Thermal resistance junction-to-mount to follow JEDEC® 51-14, transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)							
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE			
S3BJ-M3/I	0.1	I	3200	13" diameter plastic tape and reel			
S3BJ-E3/I	0.1	I	3200	13" diameter plastic tape and reel			

RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

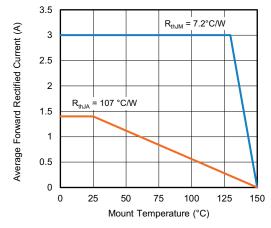


Fig. 1 - Maximum Forward Current Derating Curve

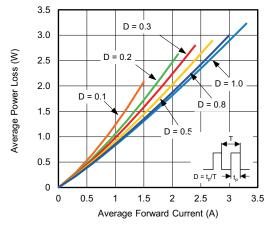


Fig. 2 - Forward Power Loss Characteristics

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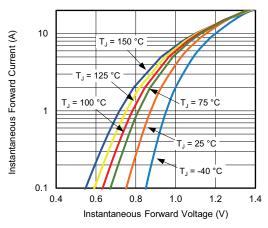


Fig. 3 - Typical Instantaneous Forward Characteristics

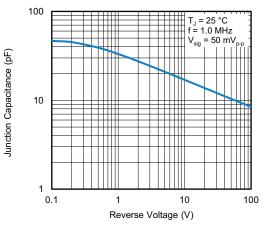


Fig. 5 - Typical Junction Capacitance

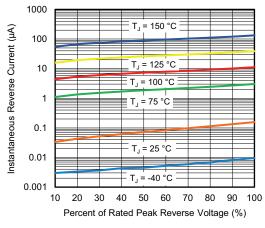


Fig. 4 - Typical Reverse Characteristics

0.060 (1.52)

0.030 (0.76)

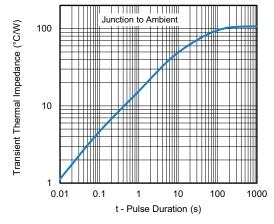


Fig. 6 - Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

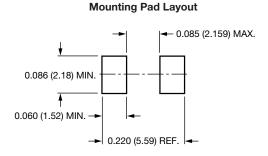
SMB (DO-214AA)

0.086 (2.20) 0.077 (1.95) 0.180 (4.57) 0.180 (4.06) 0.096 (2.44) 0.096 (2.44) 0.084 (2.13)

0.220 (5.59) 0.205 (5.21)

0.008 (0.2)

0 (0)





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